

HIGH SPEED LAN MAGNETICS

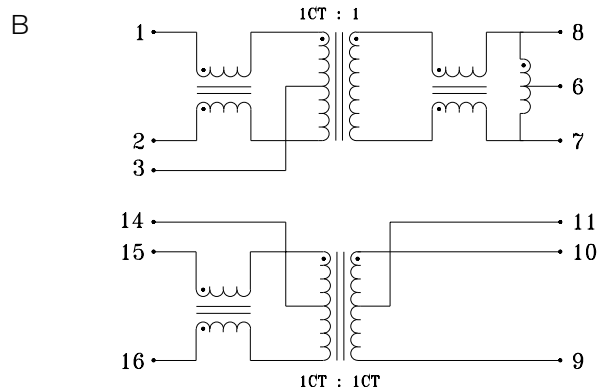
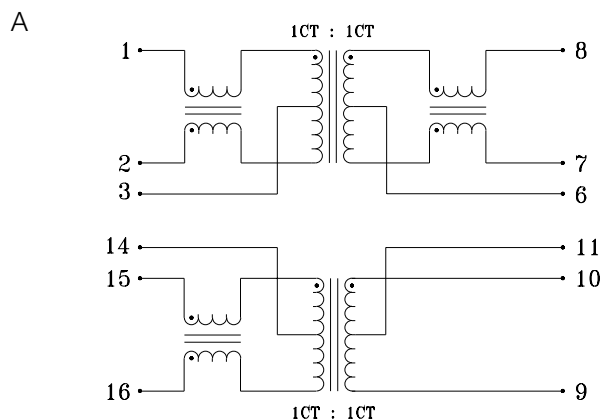
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- For use in 100Base-TX, 10/100Base-TX, ATM 155 or 100 Mbps TP-FDDI applications
- Compatible with multiple PHY transceivers
- Low profile, surface mount or through-hole packaging available
- Available with or without impedance matched common mode termination on the transmit channel

ELECTRICALS AT 25°C

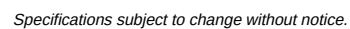
Part No.	Inductance OCL (μH) Min @8mA DC bias	Isolation Vrms Min	Insertion Loss (dB) Typ 1MHz-100MHz	CMDR (dB) Min		CMCM (dB) Min		Crosstalk (dB) Max 1MHz-100MHz	Schematic	Package Style
A558-5999-01	350	2000	-1.0	-50	-40	-40	-30	-30	A	1
S558-5999-01	350	2000	-1.0	-50	-40	-40	-30	-30	A	2
S558-5999-30	350	2000	-1.0	-50	-40	-40	-30	-30	A	3
S558-5999-42	350	2000	-1.0	-50	-40	-40	-30	-30	A	4
S558-5999-90	350	2000	-1.0	-50	-40	-40	-30	-30	B	4

SCHEMATICS



Specifications subject to change without notice.

1

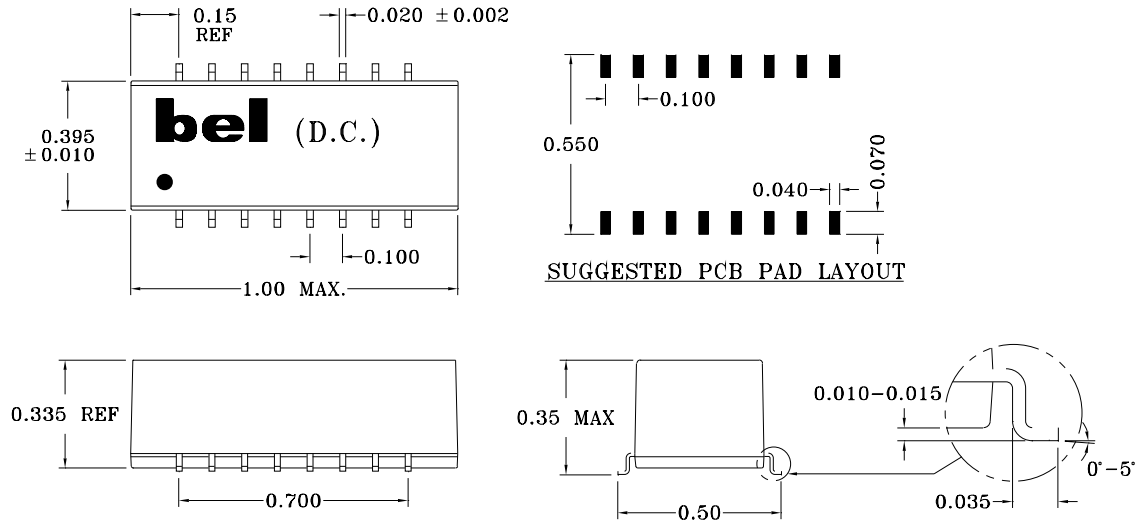


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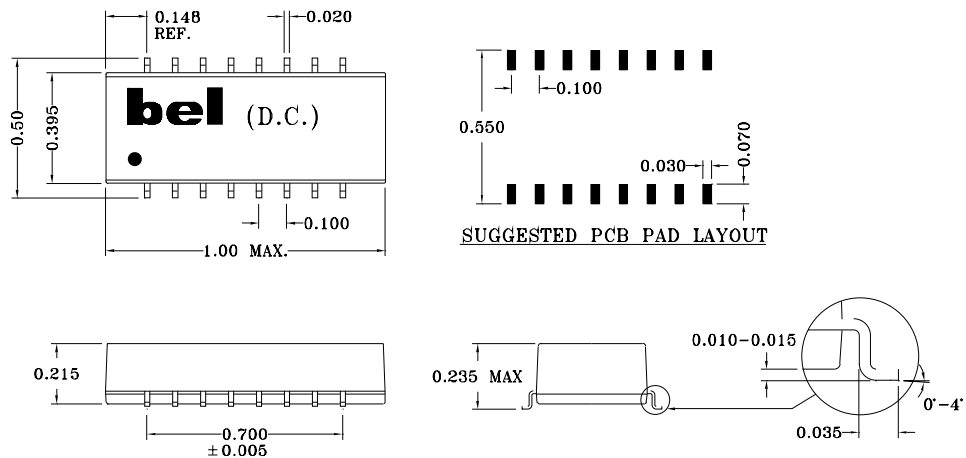
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MECHANICALS (CONT'D)

3



4

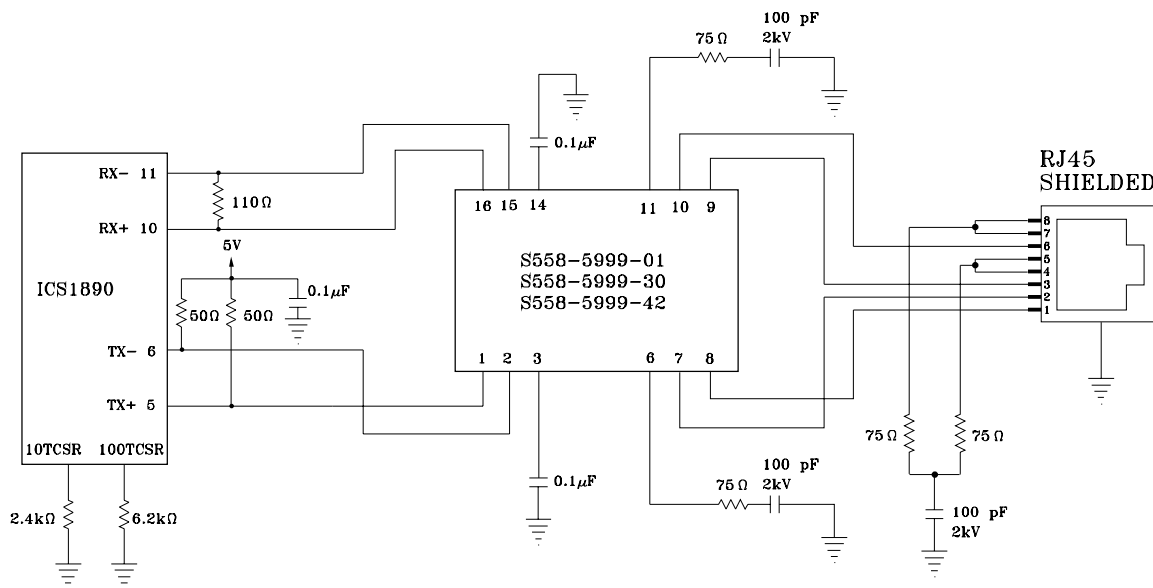


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APPLICATION CIRCUIT



APPLICATION NOTES

- These Bel part types have been designed for use in 100 Mbps TP-FDDI, 100Base-TX, 10/100Base-TX and ATM 155 Mbps applications over Category 5 UTP or STP cable.
- Each Bel part type is designed with high voltage isolation transformers and common mode chokes. The S558-5999-90 also includes an impedance matched common mode termination. For background details concerning the proper implementation or complete elimination of this termination circuit, please request Bel's separate application note available on this subject. All designs have been created to provide 350μH OCL with 8mA DC bias applied. Consult the Bel short form catalog and recommended application circuit for the specific configuration of each individual part type.
- The surface mount packages are designed for high speed pick and place machinery. Parts can be shipped on tape and reel for high speed placement. Construction processes have been implemented for thermal compatibility with high temperature IR reflow assembly processing. Post dipping of leads assist with PC board solderability. Each part is optically inspected to meet rigid coplanarity requirements.

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